



Title of Change:	Wafer fab expansion of TMOS7 devices at ON Semiconductor fab location in Niigata, Japan
Proposed first ship date:	31 October 2015
Contact information:	Contact your local ON Semiconductor Sales Office or <MohdHezri.AbuBakar@onsemi.com>
Samples:	Contact your local ON Semiconductor Sales Office
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or <Donna.Scheuch@onsemi.com>.
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>.
Change Part Identification:	Affected products will be identified with date code of WW42'15 or later.
Change category:	<input checked="" type="checkbox"/> Wafer Fab Change <input type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input type="checkbox"/> Other _____

Change Sub-Category(s):		<input type="checkbox"/> Datasheet/Product Doc change
<input checked="" type="checkbox"/> Manufacturing Site Change/Addition	<input type="checkbox"/> Material Change	<input type="checkbox"/> Shipping/Packaging/Marking
<input type="checkbox"/> Manufacturing Process Change	<input type="checkbox"/> Product specific change	<input type="checkbox"/> Other: _____
Sites Affected:		<input type="checkbox"/> External Foundry/Subcon site(s)
<input type="checkbox"/> All site(s)	<input type="checkbox"/> not applicable	<input checked="" type="checkbox"/> ON Semiconductor site(s) : ON Niigata, Japan

Description and Purpose:
 This is a final change notification to customer on the planned capacity expansion of ON Semiconductor's wafer fab operation in Niigata Japan for TMOS7 products. Upon the expiration of this notification, all products listed here will be processed at either Niigata or existing location. These products have been qualified to commodity/commercial requirements.

Reliability Data Summary
NTB35N15T4G

Test	Name	Test Conditions	Duration	Sample size	Result
HTRB	High Temp Reverse Bias	TA = 150°C, 80% rated Vdss	1008 Hrs	84pcs/3 lots	0/252
HTGB	High Temp Gate Bias	TA = 150°C, 100% rated Vgss	1008 Hrs	84pcs/3 lots	0/252
IOL-PC	Intermittent Operating Life + PC	Ta=+25°C, delta Tj=100°C On/of f= 2 min	8572 Cyc	84pcs/3 lots	0/252
TC-PC	Temperature Cycling + PC	-55°C to +150°C	1000 Cyc	84pcs/3 lots	0/252
AC-PC	Autoclave + PC	121°C/100% RH/15psig	96 Hrs	84pcs/3 lots	0/252
H3TRB - PC	High Humidity High Temp Rev Bias + Preconditioning	Ta=85°C, 85% RH, 80% rated or 100V max	1008 Hrs.	84pcs/3 lots	0/252
UHAST-PC	Unbiased Highly Accelerated Stress Test + Preconditioning	Temp= +130°C, RH=85% , p = 18.8 psig, unbiased	96 Hrs	84pcs/3 lots	0/252

NTB75N06T4G

Test	Name	Test Conditions	Duration	Sample Size	Result
HTRB	High Temp Reverse Bias	TA = 175°C, 80% rated Vdss	1008 Hrs	84pcs/3 lots	0/252
HTGB	High Temp Gate Bias	TA = 175°C, 100% rated Vgss	1008 Hrs	84pcs/3 lots	0/252

**Electrical Characteristic Summary:**

Electrical characteristics are not impacted.

List of Affected Standard Parts:

Part Number	Qualification Vehicle
NTB35N15T4G	NTB35N15T4G
NTB45N06LT4G	NTB35N15T4G
NTB60N06T4G	NTB35N15T4G
NTD20N06LT4G	NTB35N15T4G
NTD24N06LT4G	NTB35N15T4G
NTD24N06T4G	NTB35N15T4G
NTD3055-150T4G	NTB35N15T4G
NTD3055L170T4G	NTB35N15T4G
NTD3055-094T4G	NTB35N15T4G
NTD3055-094-1G	NTB35N15T4G
NTF3055-100T1G	NTB35N15T4G
NTF3055-100T3G	NTB35N15T4G